

High Performance, Resin-Blocking, Release Film



PACO•VIA RESIN-BLOCKING SYSTEM For the Lamination of Blind and Buried Via Holes

The **PACO•VIA**® Two-Component System (PACO•VIA and PACOPADS) is a performance-driven line of High-Temperature, Resin-Blocking Release Films. The **PACO•VIA** System is specifically engineered to enhance sequential lamination of Buried and Blind Via designed rigid printed Circuit Boards.

LAMINATION PROCESS ADVANTAGES

■ **Resin Containment**

PACO•VIA Resin Blocking Film contains the resin within the via barrel eliminating the need for secondary processing to remove cured resin from the panel surface.

■ **Barrel Fill**

PACO•VIA Resin Blocking Film allows the liquid resin to essentially fill the via Barrel.

■ **Contain Resin Squeeze-out**

PACO•VIA contains resin squeeze-out like traditional release films while offering superior copper surface buffering from damaged Separator Plates.

■ **Equalization of Pressure Throughout the Pressure Load**

The PACOPADS component of the PACO•VIA System ensures complete barrel fill, and controlled Dielectric Thickness. The PACOPADS eliminate air voids, inner-layer slippage and white corners or edges. PACOPADS also reduce image and glass cloth Transfer, and alleviate the potential of low-pressure prepreg Blisters. See PACOPADS Product Information Bulletin.

PACO•VIA SYSTEM FEATURES

- Three engineered Grades to fit all sequential lamination demands.
- Choice of PACOPADS Pressure Equalizing Press Pads designed to suit all lamination process parameters.
- Operating temperature of 425°F / 218°C for up to 4 hours.
- Proven worldwide performance since 1996.

